

# 74HC244; 74HCT244

Octal buffer/line driver; 3-state

Rev. 8 — 5 August 2024

Product data sheet

## 1. General description

The 74HC244; 74HCT244 is an 8-bit buffer/line driver with 3-state outputs. The device can be used as two 4-bit buffers or one 8-bit buffer. The device features two output enables ( $1\text{OE}$  and  $2\text{OE}$ ), each controlling four of the 3-state outputs. A HIGH on  $n\text{OE}$  causes the outputs to assume a high-impedance OFF-state. Inputs include clamp diodes that enable the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

## 2. Features and benefits

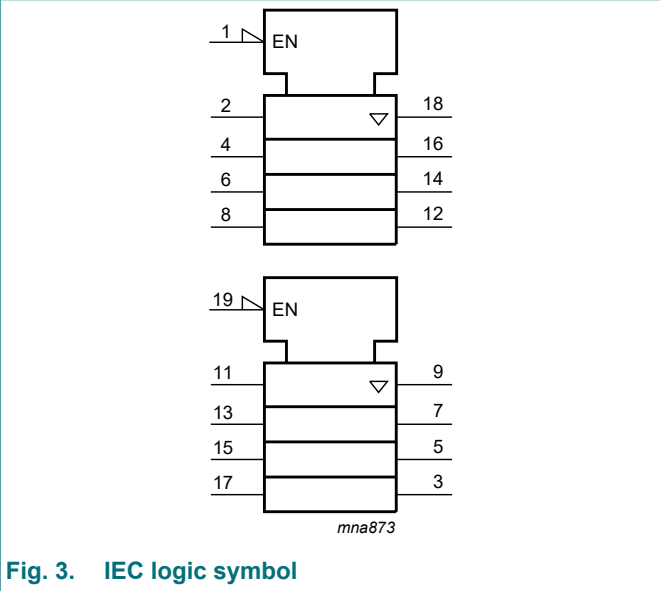
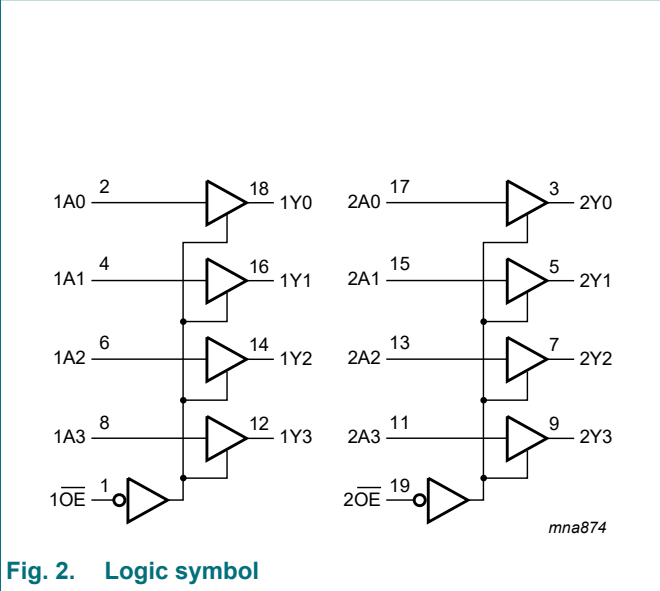
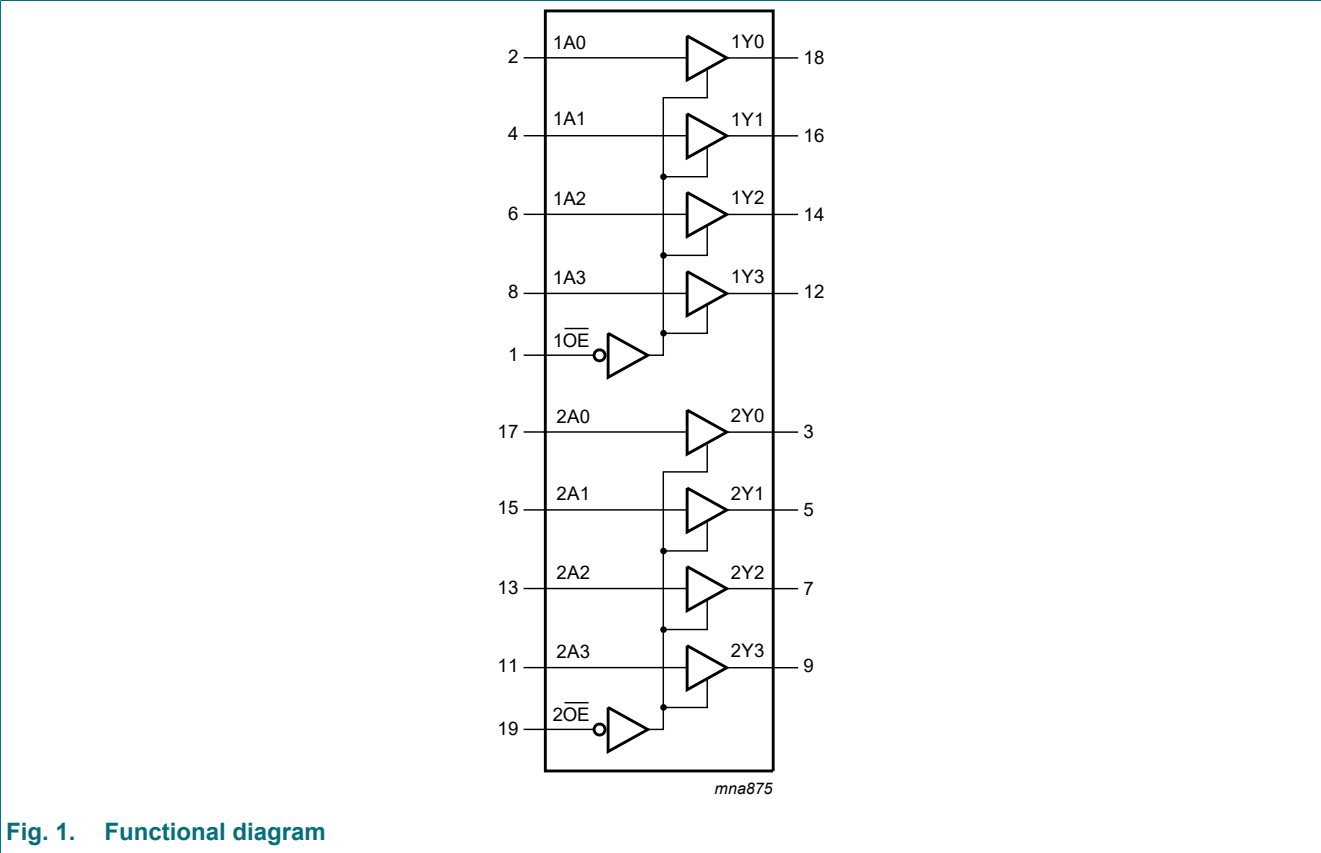
- Wide supply voltage range from 2.0 V to 6.0 V
- CMOS low power dissipation
- High noise immunity
- Latch-up performance exceeds 100 mA per JESD 78 Class II Level B
- Input levels:
  - For 74HC244: CMOS level
  - For 74HCT244: TTL level
- Octal bus interface
- Non-inverting 3-state outputs
- Complies with JEDEC standards:
  - JESD8C (2.7 V to 3.6 V)
  - JESD7A (2.0 V to 6.0 V)
- ESD protection:
  - HBM: ANSI/ESDA/JEDEC JS-001 class 2 exceeds 2000 V
  - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

## 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
<a href="#">74HC244D</a> <a href="#">74HCT244D</a>	-40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	<a href="#">SOT163-1</a>
<a href="#">74HC244PW</a> <a href="#">74HCT244PW</a>	-40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	<a href="#">SOT360-1</a>
<a href="#">74HC244BQ</a> <a href="#">74HCT244BQ</a>	-40 °C to +125 °C	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	<a href="#">SOT764-1</a>

4. Functional diagram



5. Pinning information

5.1. Pinning

**D package**  
**SOT163-1 (SO20)**

aaa-035023

**PW package**  
**SOT360-1 (TSSOP20)**

aaa-035024

**BQ package**  
**SOT764-1 (DHVQFN20)**

aaa-035028

Transparent top view

(1) This is not a ground pin. There is no electrical or mechanical requirement to solder the pad. In case soldered, the solder land should remain floating or connected to GND.

5.2. Pin description

Table 2. Pin description

Symbol	Pin	Description
1OE, 2OE	1, 19	output enable input (active LOW)
1A0, 1A1, 1A2, 1A3	2, 4, 6, 8	data input
2Y0, 2Y1, 2Y2, 2Y3	3, 5, 7, 9	bus output
GND	10	ground (0 V)
2A0, 2A1, 2A2, 2A3	17, 15, 13, 11	data input
1Y0, 1Y1, 1Y2, 1Y3	18, 16, 14, 12	bus output
VCC	20	supply voltage

6. Functional description

Table 3. Function table

H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

Input		Output
nOE	nAn	nYn
L	L	L
L	H	H
H	X	Z

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V or V <sub>I</sub> > V <sub>CC</sub> + 0.5 V	-	±20	mA
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < -0.5 V or V <sub>O</sub> > V <sub>CC</sub> + 0.5 V	-	±20	mA
I <sub>O</sub>	output current	-0.5 V < V <sub>O</sub> < V <sub>CC</sub> + 0.5 V	-	±35	mA
I <sub>CC</sub>	supply current		-	70	mA
I <sub>GND</sub>	ground current		-70	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	[1]	-	500	mW

[1] For SOT163-1 (SO20) package: P<sub>tot</sub> derates linearly with 12.3 mW/K above 109 °C.  
For SOT360-1 (TSSOP20) package: P<sub>tot</sub> derates linearly with 10.0 mW/K above 100 °C.  
For SOT764-1 (DHVQFN20) package: P<sub>tot</sub> derates linearly with 12.9 mW/K above 111 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
74HC244						
V <sub>CC</sub>	supply voltage		2.0	5.0	6.0	V
V <sub>I</sub>	input voltage		0	-	V <sub>CC</sub>	V
V <sub>O</sub>	output voltage		0	-	V <sub>CC</sub>	V
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 2.0 V	-	-	625	ns/V
		V <sub>CC</sub> = 4.5 V	-	1.67	139	ns/V
		V <sub>CC</sub> = 6.0 V	-	-	83	ns/V
T <sub>amb</sub>	ambient temperature		-40	-	+125	°C
74HCT244						
V <sub>CC</sub>	supply voltage		4.5	5.0	5.5	V
V <sub>I</sub>	input voltage		0	-	V <sub>CC</sub>	V
V <sub>O</sub>	output voltage		0	-	V <sub>CC</sub>	V
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 4.5 V	-	1.67	139	ns/V
T <sub>amb</sub>	ambient temperature		-40	-	+125	°C

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC244										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -20 µA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 µA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 µA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -6.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I <sub>O</sub> = -7.8 mA; V <sub>CC</sub> = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 20 µA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 µA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 µA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 6.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I <sub>O</sub> = 7.8 mA; V <sub>CC</sub> = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	µA
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 6.0 V; V <sub>O</sub> = V <sub>CC</sub> or GND	-	-	±0.5	-	±5.0	-	±10	µA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8.0	-	80	-	160	µA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HCT244										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -20 µA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -6 mA	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 20 µA	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 6.0 mA	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	µA
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 5.5 V; V <sub>O</sub> = V <sub>CC</sub> or GND	-	-	±0.5	-	±5.0	-	±10	µA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V; I <sub>O</sub> = 0 A	-	-	8.0	-	80	-	160	µA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V; I <sub>O</sub> = 0 A	-	70	252	-	315	-	343	µA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

$GND = 0\text{ V}$ ; for test circuit see Fig. 6.

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC244										
t <sub>pd</sub>	propagation delay	nAn to nYn; see Fig. 4 [1]								
		V <sub>CC</sub> = 2.0 V	-	30	110	-	145	-	165	ns
		V <sub>CC</sub> = 4.5 V	-	11	22	-	28	-	33	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	9	-	-	-	-	-	ns
		V <sub>CC</sub> = 6.0 V	-	9	19	-	24	-	28	ns
t <sub>en</sub>	enable time	nOE to nYn; see Fig. 5 [2]								
		V <sub>CC</sub> = 2.0 V	-	36	150	-	190	-	225	ns
		V <sub>CC</sub> = 4.5 V	-	13	30	-	38	-	45	ns
		V <sub>CC</sub> = 6.0 V	-	10	26	-	33	-	38	ns
t <sub>dis</sub>	disable time	nOE to nYn; see Fig. 5 [3]								
		V <sub>CC</sub> = 2.0 V	-	39	150	-	190	-	225	ns
		V <sub>CC</sub> = 4.5 V	-	14	30	-	38	-	45	ns
		V <sub>CC</sub> = 6.0 V	-	11	26	-	33	-	38	ns
t <sub>t</sub>	transition time	see Fig. 4 [4]								
		V <sub>CC</sub> = 2.0 V	-	14	60	-	75	-	90	ns
		V <sub>CC</sub> = 4.5 V	-	5	12	-	15	-	18	ns
		V <sub>CC</sub> = 6.0 V	-	4	10	-	13	-	15	ns
C <sub>PD</sub>	power dissipation capacitance	per buffer; V <sub>I</sub> = GND to V <sub>CC</sub> [5]	-	35	-	-	-	-	-	pF
74HCT244										
t <sub>pd</sub>	propagation delay	nAn to nYn; see Fig. 4 [1]								
		V <sub>CC</sub> = 4.5 V	-	13	22	-	28	-	33	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	11	-	-	-	-	-	ns
t <sub>en</sub>	enable time	nOE to nYn; V <sub>CC</sub> = 4.5 V; see Fig. 5 [2]	-	15	30	-	38	-	45	ns
t <sub>dis</sub>	disable time	nOE to nYn; V <sub>CC</sub> = 4.5 V; see Fig. 5 [3]	-	15	25	-	31	-	38	ns
t <sub>t</sub>	transition time	V <sub>CC</sub> = 4.5 V; see Fig. 4 [4]	-	5	12	-	15	-	18	ns
C <sub>PD</sub>	power dissipation capacitance	per buffer; V <sub>I</sub> = GND to V <sub>CC</sub> - 1.5 V [5]	-	35	-	-	-	-	-	pF

[1]  $t_{pd}$  is the same as  $t_{PHL}$  and  $t_{PLH}$ .

[2]  $t_{en}$  is the same as  $t_{PZH}$  and  $t_{PZL}$ .

[3]  $t_{dis}$  is the same as  $t_{PHZ}$  and  $t_{PLZ}$ .

[4]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .

[5]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ):  $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma (C_L \times V_{CC}^2 \times f_o)$  where:

$f_i$  = input frequency in MHz;  $f_o$  = output frequency in MHz;

$C_L$  = output load capacitance in pF;  $V_{CC}$  = supply voltage in V;

$N$  = number of inputs switching;  $\Sigma (C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

10.1. Waveforms and test circuit

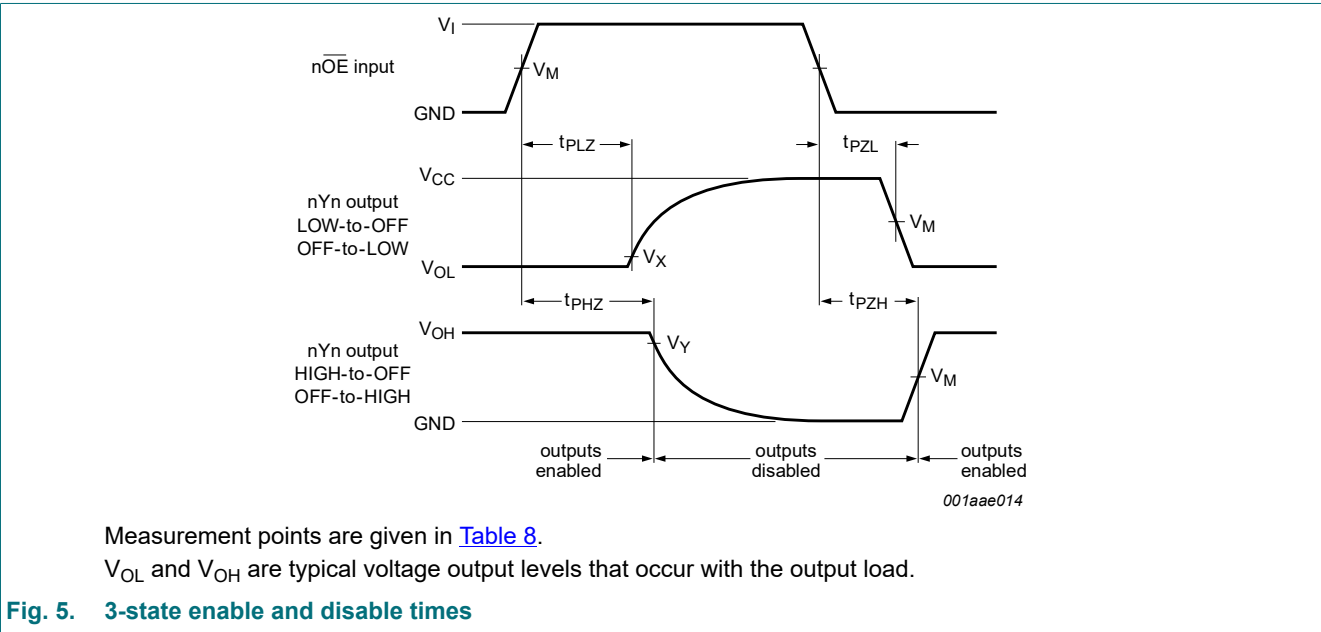
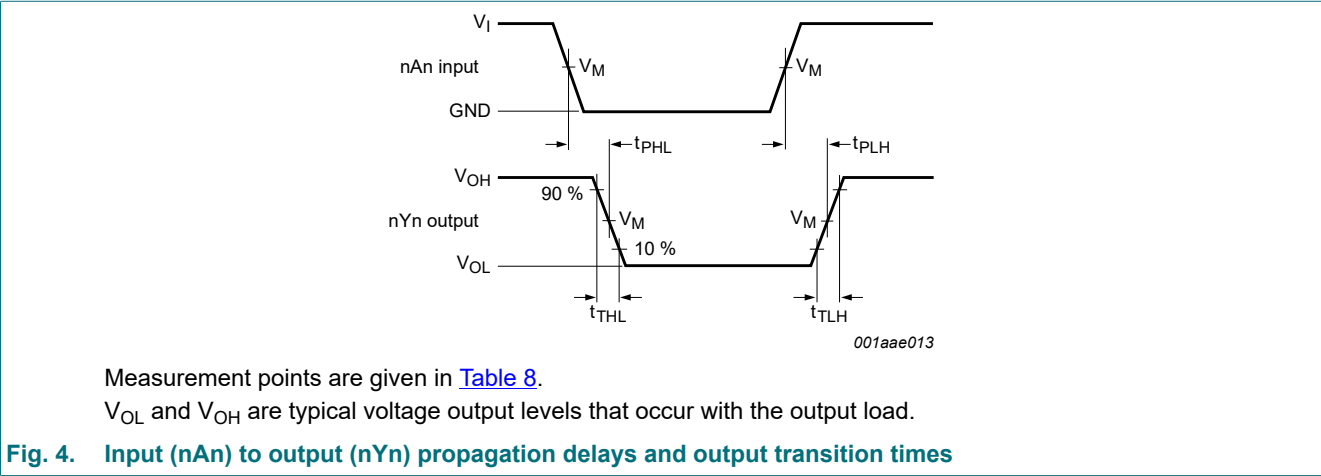


Table 8. Measurement points

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74HC244	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$0.1 \times V_{CC}$	$0.9 \times V_{CC}$
74HCT244	1.3 V	1.3 V	$0.1 \times V_{CC}$	$0.9 \times V_{CC}$



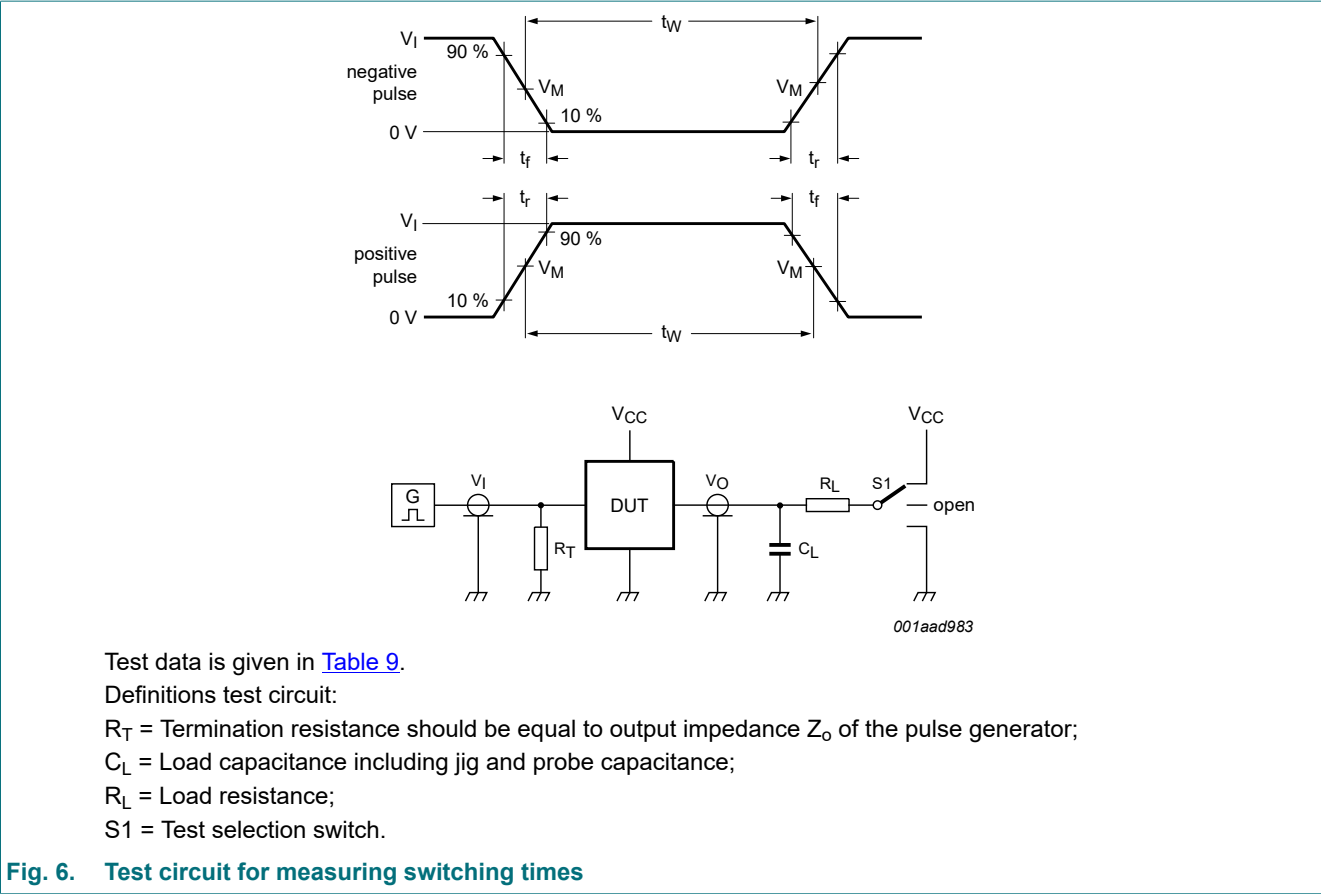


Table 9. Test data

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74HC244	$V_{CC}$	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$
74HCT244	3 V	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$

11. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



Fig. 7. Package outline SOT163-1 (SO20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

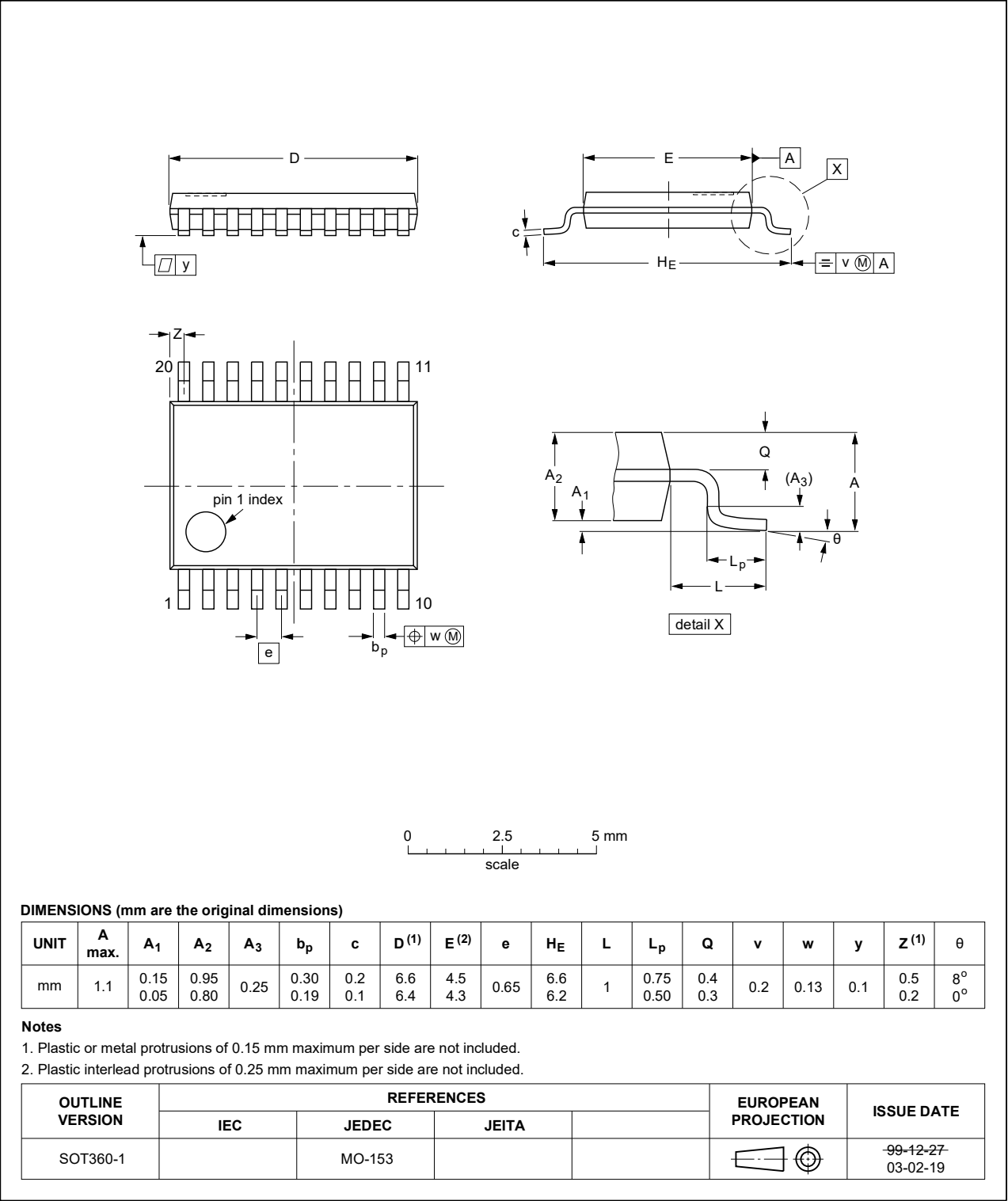


Fig. 8. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;  
20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1

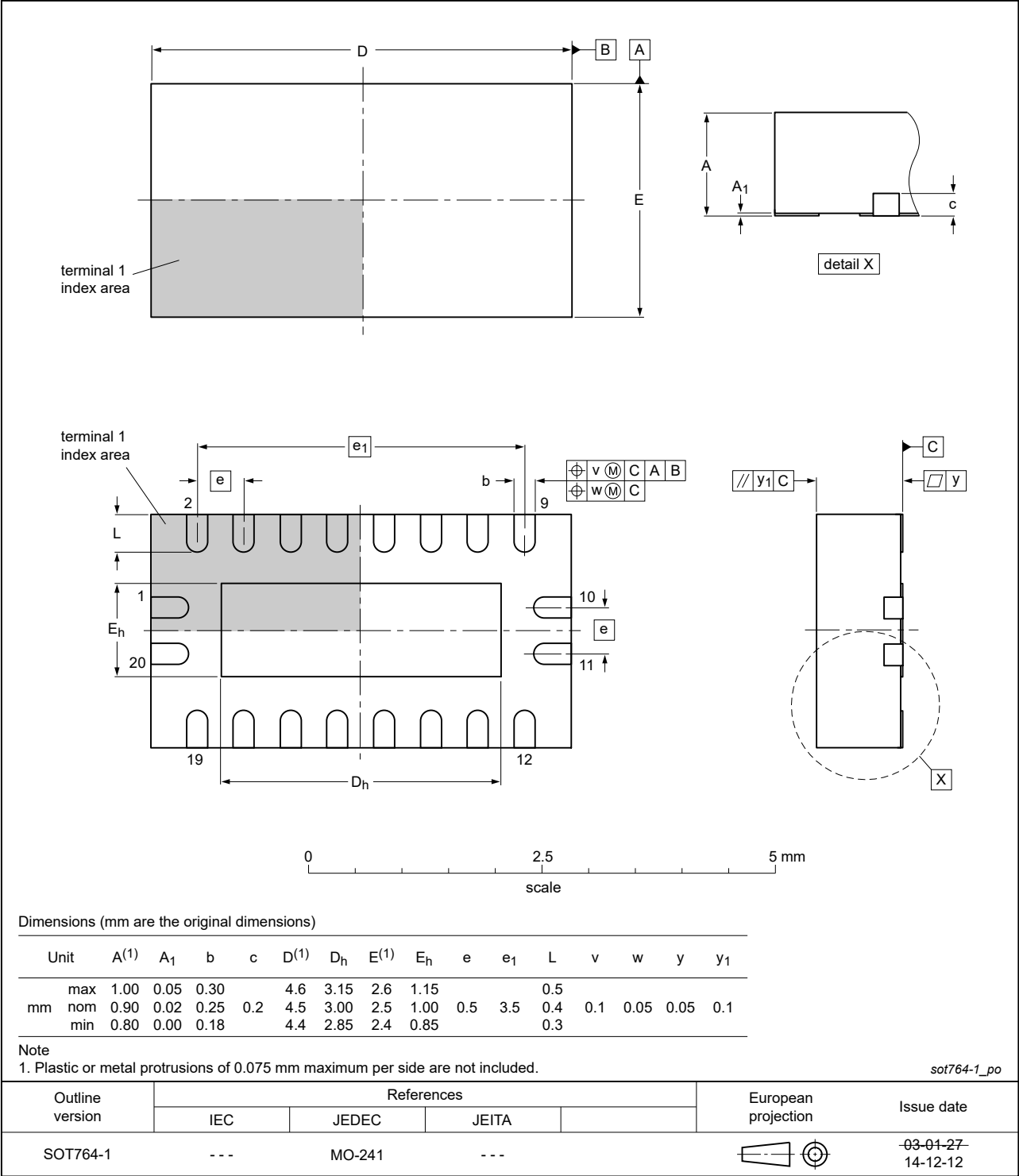


Fig. 9. Package outline SOT764-1 (DHVQFN20)

12. Abbreviations

Table 10. Abbreviations

Acronym	Description
ANSI	American National Standards Institute
CDM	Charged Device Model
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
ESDA	ElectroStatic Discharge Association
HBM	Human Body Model
JEDEC	Joint Electron Device Engineering Council
TTL	Transistor-Transistor Logic

13. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT244 v.8	20240805	Product data sheet	-	74HC_HCT244 v.7
Modifications:	<ul style="list-style-type: none"><li>• <a href="#">Section 2</a>: ESD specification updated according to the latest JEDEC standard.</li></ul>			
74HC_HCT244 v.7	20210727	Product data sheet	-	74HC_HCT244 v.6
Modifications:	<ul style="list-style-type: none"><li>• Type numbers 74HC244DB and 74HCT244DB (SOT339-1/SSOP20) removed.</li><li>• <a href="#">Section 2</a> updated.</li></ul>			
74HC_HCT244 v.6	20190927	Product data sheet	-	74HC_HCT244 v.5
Modifications:	<ul style="list-style-type: none"><li>• The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia.</li><li>• Legal texts have been adapted to the new company name where appropriate.</li><li>• <a href="#">Table 4</a>: Derating values for P<sub>tot</sub> total power dissipation have been updated.</li></ul>			
74HC_HCT244 v.5	20160226	Product data sheet	-	74HC_HCT244 v.4
Modifications:	<ul style="list-style-type: none"><li>• Type numbers 74HC244N and 74HCT244N (SOT146-1) removed.</li></ul>			
74HC_HCT244 v.4	20120924	Product data sheet	-	74HC_HCT244 v.3
Modifications:	<ul style="list-style-type: none"><li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>• Legal texts have been adapted to the new company name where appropriate.</li></ul>			
74HC_HCT244 v.3	20051222	Product data sheet	-	74HC_HCT244_CNV v.2
74HC_HCT244_CNV v.2	19901201	Product specification	-	-

## 14. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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